技术数据表

[redacted] ）：

* L/W/H :4.6*4.5*2.5 mm

Outline Dimensions (L / w / h): 4.6x 4.5 x 2.5mm

* [illegible] :

Luminous color and colloid: infrared receiver tube /transparent colloid

* ROHS

Environmental protection products Complied With ROHS Directive

* MSL :3

Moisture sensitivity level MSL :3 levels

* EIA

EIA standard packaging

*

High energy efficiency, fast startup

应用领域（ ）：

*

Medical

目录

Catalogue

电性参数

ǎ O	ˆ		ϒ
w Power consumption	Pd	75	mW
ǔ ϒ	VCEO	30	V
ǔ - ϒ	VECO	5	V
	IC(ON)	20	mA
Operating ambient temperature	Topr	-20ÁC ~ +85ÁC	
Storage ambient temperature	Tstg	-40ÁC ~ +85ÁC	
Welding conditions	Tsol	reflow soldering 260ÁC 6s manual welding 300ÁC 3s ضي2.0mm	

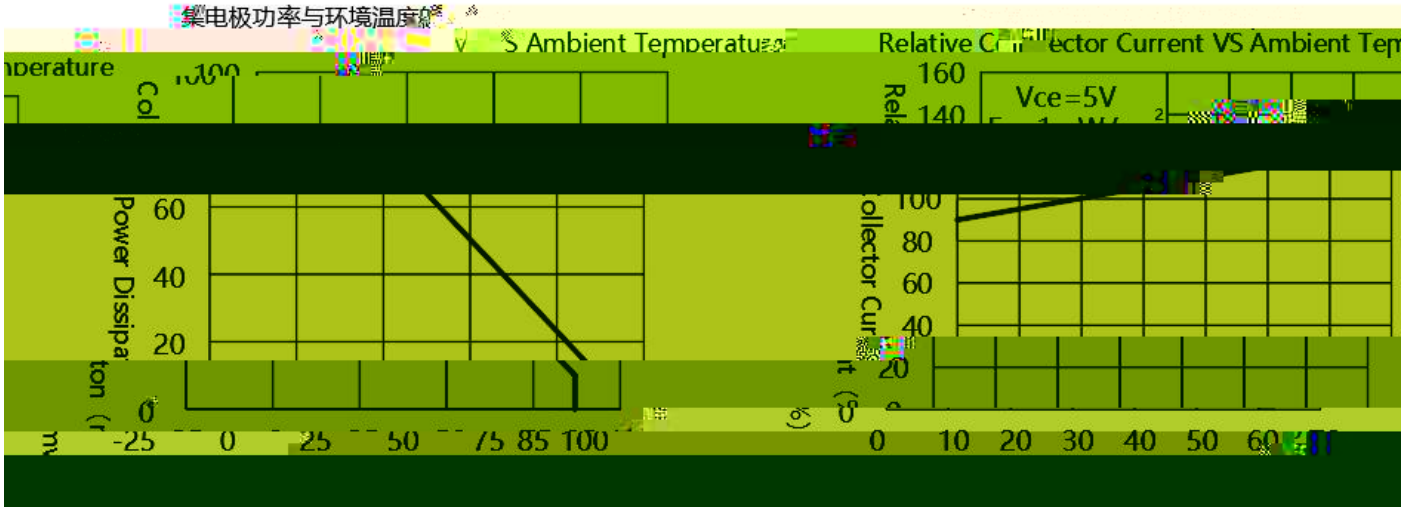
* Ⅱ ≤0. 1ms \l ≤1/10
* Note: Pulse width≤0. 1ms, Duty≤1/10

ǎ

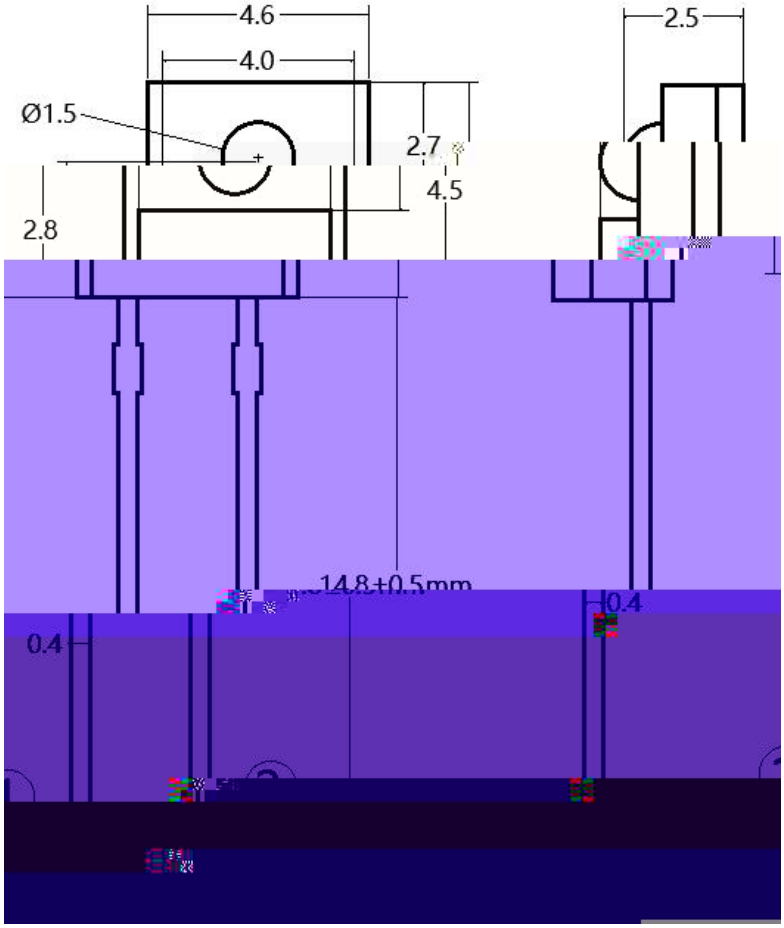
ǎ	ˇ				˥	
- ǔ Ɗρ ˥ Collector emitter breakdown voltage	Vbr ceo	30	/	/	V	IC=100εA Ee=0mW/cm2
ǔ - Ɗρ ˥ Emitter to collector breakdown voltage	Vbr eco	5	/	/	V	IC=100εA Ee=0mW/cm2
- ǔ ˥ Collector-EmitterSaturationVoltage	Vce(SAT)	/	/	0.4	V	IC=2mA Ee=1mW/cm2
Collector dark current	Io	/	/	100	nA	Ee=0mW/cm2 VCE=20V

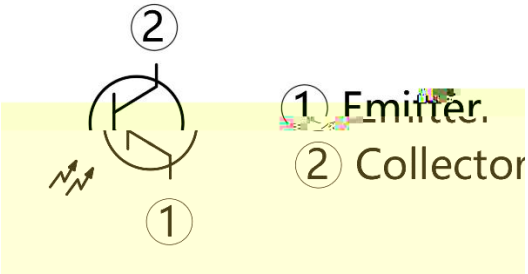
˦

典型特性曲线


集电极功率与环境温度
Ambient Temperature
Relative Collector Current VS Ambient Tem
Vce=5V
Power Dissipation (mW)
Relative Collector Current (%)
60
40
20
0
-25
0
25
50
75
85
100
160
140
120
100
80
60
40
20
0
10
20
30
40
50
60

外形尺寸





(Note)

1. 丶

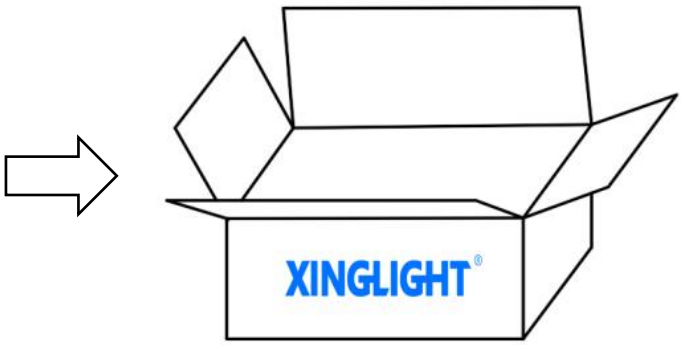
Dimensions are in millimeters

2. ≠ 乚 Ñ 030mm

Tolerances unless mentioned are Ñ 0.30mm

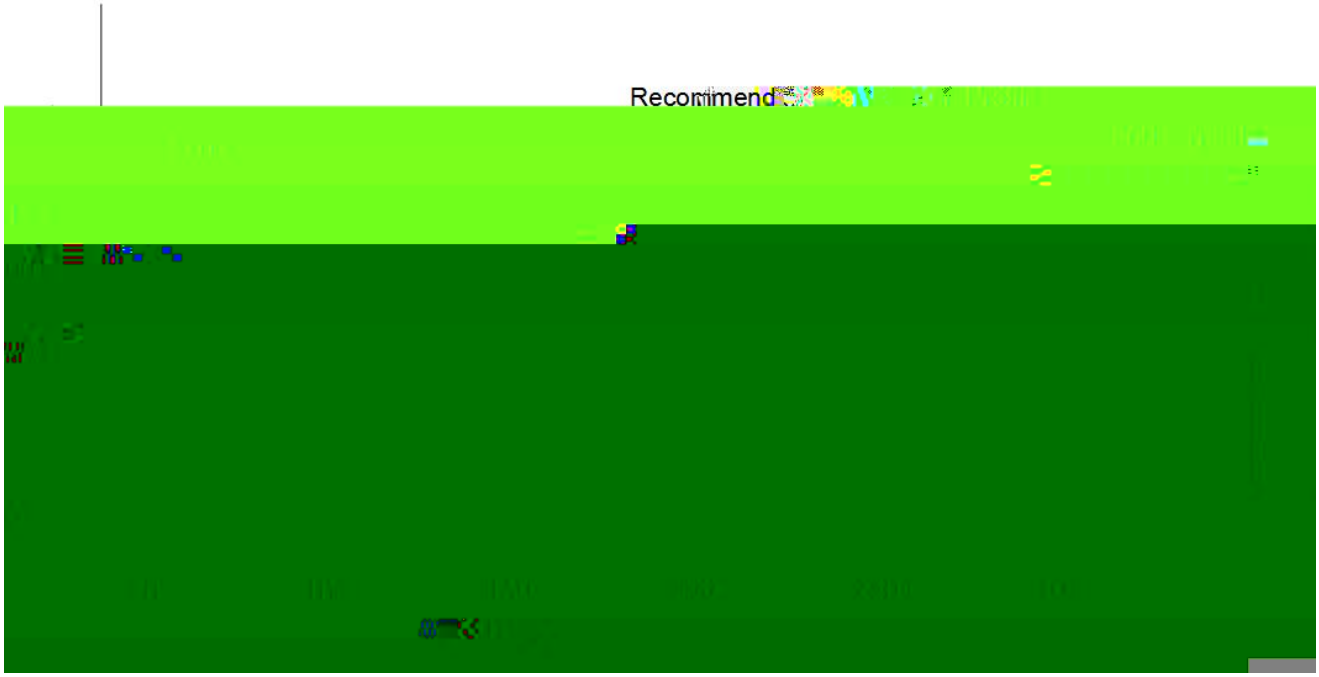
包装（ ）

Moist e Proof and Antti-Electrostic Foil Bag



焊接指导

The wave peak welding curve is recommended :



Note

1

Lead solder temperature profile

2

Suggest one wave soldering frequency

3 LED

When soldering, do not put stress on the LED during heating

4

After soldering, do not warp the circuit board

5 240 /6S

The recommended maximum welding temperature for the product is 240 /6s

Soldering Iron

300 3 ṗ 25W U

ضي

Each terminal is to go to the ti dering iron temper s than 300 for seconds with ss than the soldering iron capa W. Leave two seconds re intervals soldering of eac al. Be careful because the damage of the time of the

手工 Repairing

ضي LED U ّأ (يد)

LED ٦ شخ

Repair should not be done after the LED have ered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure

使用注意事项(2)

1.

LED W`E LED ضي

This LED can be used in some ordinary electronic equipment, such as office equipment, communication equipment, house decoration, if LED is used in some high reliability requirements, such as air transportation, traffic control and medical liao equipment, must refer to the information provided by sales.

LED 30 70% LEDضي

Storage environment of LED with temperature not exceeding 30 and relative humidity not exceeding 70%.It is recommended that LDE be used in the original box for no more than three months. If longer storage time is required, put it in the drying box and add desiccant or filled with nitrogen.

ضي 3№

Special care must be taken when cleaning colloids with chemicals, as some chemicals have damage to the colloidal surface and cause fading such as trichloroethylene, propylene, ketone, etc.It can be wiped and soaked with ethanol for no more than 3 minutes at room temperature.

1 2

It must be 2 mm from the brack

2

Support forming must be do ith fix s or by fessio

3 ضي

Support forming must be completed before welding.

4

The pins &ri A & the same & on the circuit "o&l.

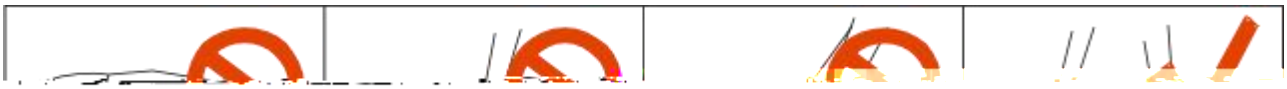
5 ضي LED PCB U ضيLED

使用注意事项（3）

Precautions (3)

8、其他事项：

*When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



*The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.